

SPIRE IF Meeting Agenda, Tuesday 6 May 2003
From 08:30 to 17:30

Actions status:**Actions from HP-ASPI-MN-2298 (26-27/11/02):**

AI-2 SPIRE, Update IID-B, still open

§5.16: Add hardware matrix (deliverable items)

§ 5: details of all points of electrical isolation on SPIRE FPU & JFETs.

§9: provide input wrt testing & verification

Actions from HP-ASPI-MN-2748 (27/2/03):

- AI-1 SPIRE : ECR 29 updated in v3.0, with harness document 1.1, closed by CR291 sent to ASED by ASP
- AI-2 ASP+ASED : closed, simplified temperature sensors table proposed by ASP (mail H-P-ASP-LT-3035 BC 23/04) "SPIRE CR 30 reduced CCU Measurement.doc"
- AI-3 ASP : IIDB 2.3 draft 2, open (planned end April)
- AI-4 SPIRE : make provision for inserts to support harness, open ? (mail JD 21/03 + drawing)
- AI-5 SPIRE : Tolerances to be added to the JFET rack feet position, open
- AI-6 SPIRE : refine the heat flow requirement for evaporator strap, open
- AI-7 SPIRE+ASP : ECR 9 to be reissued ; to be closed by ASP (ASP will issue a new ECR9)
- AI-8 ASP : MGSE interfaces (slide 6) to be added in IID-A, to be done by ASP in next IIDA issue end May
- AI-9 SPIRE : Integration procedure of FPU on Optical bench, open
- AI-10 SPIRE : Sorption cooler-Demonstration of the leak before burst requirement, open
- AI-11 SPIRE : Size of external Power supplies shall be given for QM test, open (partially closed)
- AI-12 ASP : Peak up mode, to be done by ASP in next IIDA issue end May
- AI-13 SPIRE+ASED : inputs/comments for IIDB 2.3 draft 1, open for SPIRE, nearly closed for ASED

Additional Action Items (Open or to be closed with formal reference):

- HP-2-ASED-MN-0182\03, RAL/JD to evaluate the IF to optimise the thermal IF, Due: 15.12.02
- HP-2-ASED-MN-0182\08, MSSL/BW should clarify how the SPIRE red tagged cover should be represented in the IF drawings, Due: 28.02.03
- HP-2-ASED-MN-0343\02, SPIRE: Update Instrument RTMM to model the heat switch as agreed in HP-2-ASED-MN-0330, Due: 11.04.03
- Status: to be closed. ITMM, Version 2.4 sent by email
- HP-2-ASED-MN-0343\04, SPIRE and PACS: To assess the change of cooler IF from M3 to M4 and initiate the change request to CEA, Due: 10.04.03
- Status: to be closed
- HP-2-ASED-MN-0343\05, SPIRE and PACS: to provide to CEA the cooler characterisation constraints for the testing, Due: 07.04.03

ECR status (with last SPIRE CR status list and CCB from ASP) :**IID-B Update v2.3 draft status and comments:**

- Inputs required

IID-A Update comments:

SPIRE general (or particular) technical status (TBD by SPIRE) :

- SPIRE schedule
- Proposed new model philosophy and schedule

Mechanical IF Issues:

- Status of updated drawings (ECR 40 + ...)
- Drawings & Interfaces for QM (and external power supply)
- Release of Issue A of Optical Bench Assembly I/F, dated March 2003
- Details of SPIRE flexible Level-0 thermal straps (material properties, etc)
- Status of FPU Feet re-design (consideration of shimming plates in the new foot design)

Thermal IF Issues:

- Re-issue of ECR#009
- SPIRE thermal model status & Clarification of TMM interface issues
- Status of Thermal Interface in preparation of Sener Delta-PDR

Electrical IF Issues:

- Status of Connectors (Glenair, Cannon, Cristek, Courage, ...)
Cryo-Harness connector issues (see request for info, ref. HP-ASED-FX-0342-03, 22.04.03):
 - Provision of sample connectors from Crystek and Courage for initial qual. tests
- SPIRE harness (cryo and WU) definition status
 - Review of SPIRE Cryo-Harness Data Package (Update of HEPLM Electrical ICD)
 - Internal over-shield status
SPIRE ECR#039 / ASPI-CR-0265 (new grounding and screening philosophy)

Optical IF Issues:

- Beams clearance analysis: Update of IF drawings and check of margins on instrument and spacecraft side

Other:

- Position of accelerometer during instrument testing
- Procurement of JFET mounting hardware for MTDs

Minutes and actions, EOM